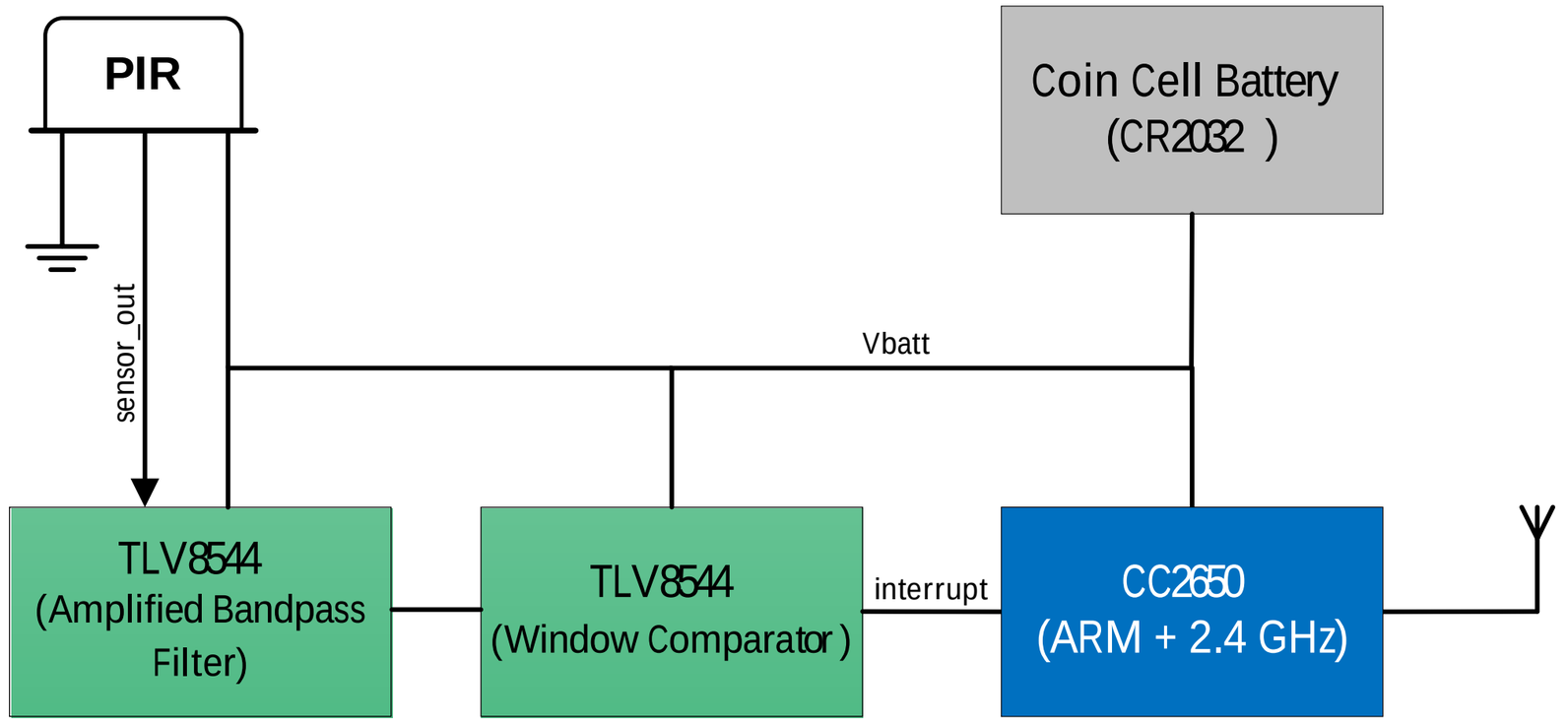
Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
E1	N/A	29 Jan 2016	Gustavo Martinez	Initial Release



Orderable: N/A		Designed for: Not for Public Release	Mod. Date: 1/27/2017
TID #: TIDA-01398		Project Title: Ultra Low-Power Wireless PIR Motion Detector for C	
Number: TIDA-01398	Rev: E1	Sheet Title: Cover Sheet	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 1 of 4
Drawn By: Gustavo Martinez		File: TIDA01398_CoverSheet.SchDoc	Size: B
Engineer: Nikhil Dua		Contact: http://www.ti.com/support	

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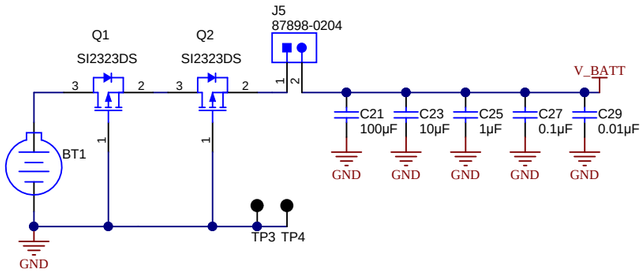
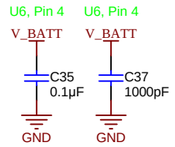
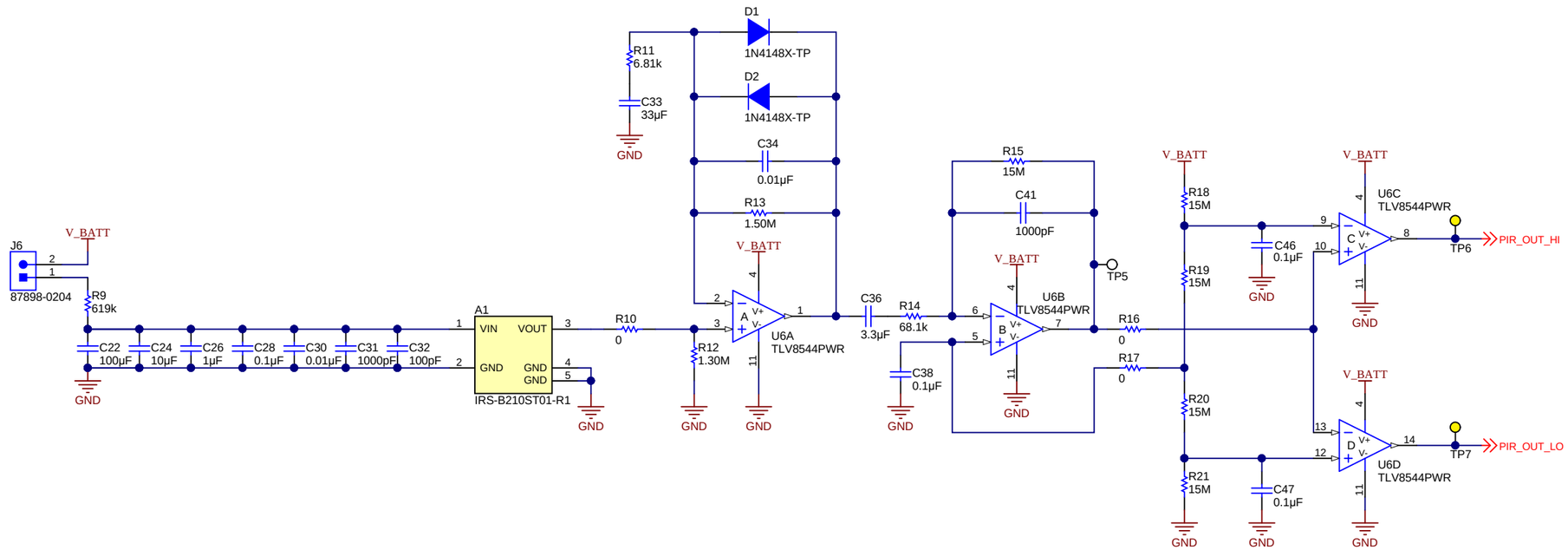
Battery Connector & Reservoir Capacitors



PIR Bypass Capacitors



PIR Sensor Signal Conditioning



Orderable: N/A	Designed for: Not for Public Release	Mod. Date: 2/22/2017
TID #: TIDA-01398	Project Title: Ultra Low-Power Wireless PIR Motion Detector for C	
Number: TIDA-01398 Rev: E1	Sheet Title: Power and PIR Sensor	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 4
Drawn By: David Stout	File: TIDA01398_POWER_PIR.SchDoc	Size: B
Engineer: Nikhil Dua	Contact: http://www.ti.com/support	

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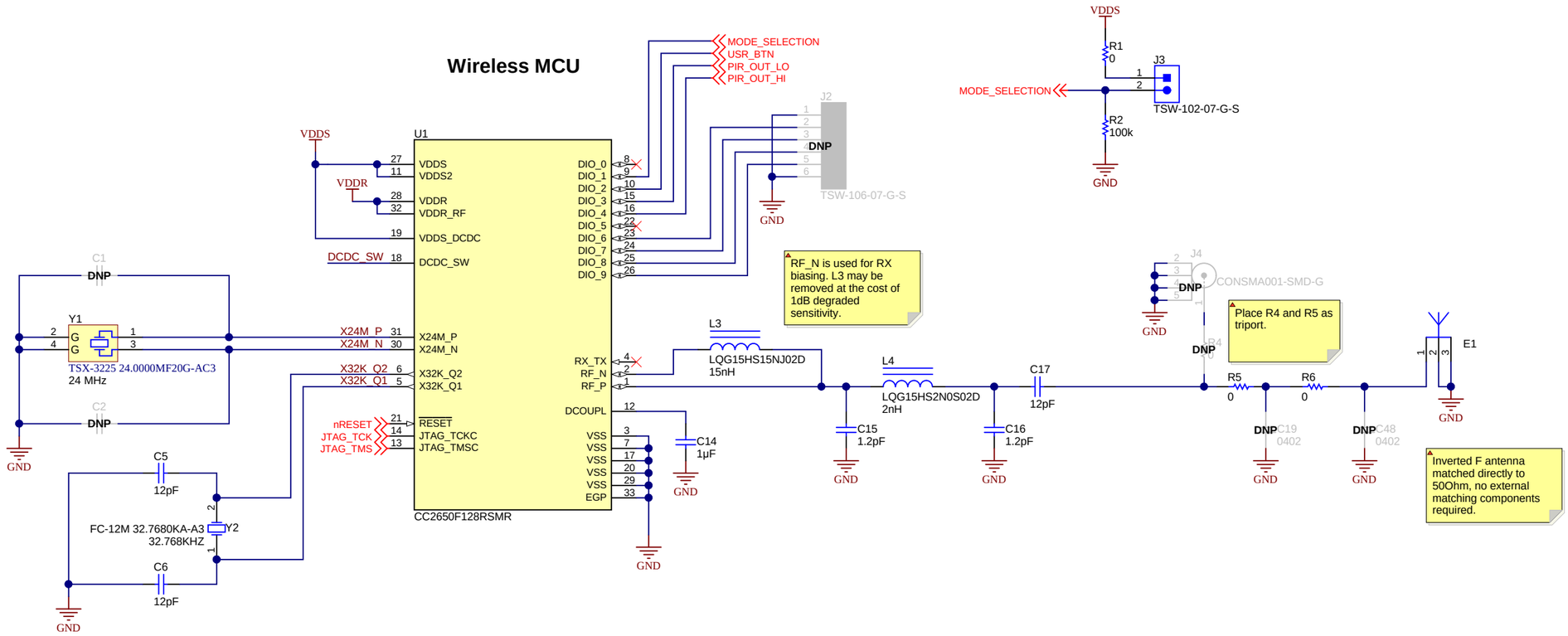
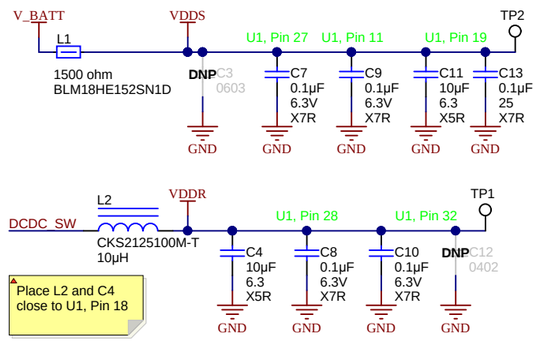
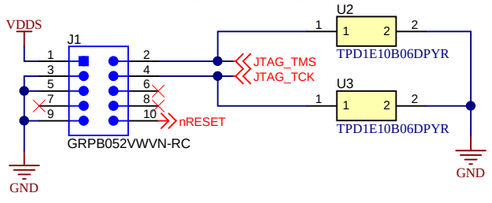
Wireless MCU



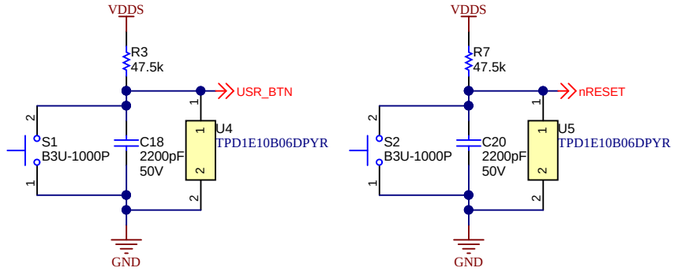
Wireless MCU Bypass Capacitors & DC-DC Passives



JTAG Programming Interface



User and Reset Switches



Orderable: N/A	Designed for: Not for Public Release	Mod. Date: 1/18/2017
TID #: TIDA-01398	Project Title: Ultra Low-Power Wireless PIR Motion Detector for C	
Number: TIDA-01398 Rev: E1	Sheet Title: Wireless MCU	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 4
Drawn By: Gustavo Martinez	File: TIDA01398_MCU.SchDoc	Size: B
Engineer: Nikhil Dua	Contact: http://www.ti.com/support	

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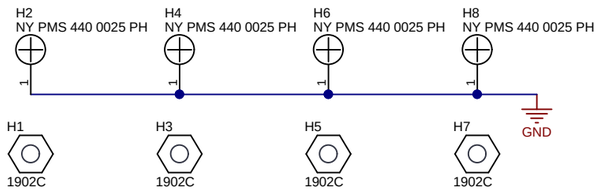

PCB Number: TIDA-01398
PCB Rev: E1

PCB
LOGO
Pb-Free Symbol

PCB
LOGO
FCC disclaimer

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ4
Assembly Note
After verifying lens of A1 is clean and undistorted, snap cover H9 over sensor A1 during final hardware assembly.

Orderable: N/A	Designed for: Not for Public Release	Mod. Date: 2/22/2017
TID #: TIDA-01398	Project Title: Ultra Low-Power Wireless PIR Motion Detector for G	
Number: TIDA-01398 Rev: E1	Sheet Title: Hardware	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 4 of 4
Drawn By: Gustavo Martinez	File: TIDA01398_TID_Hardware.SchDoc	Size: B
Engineer: Nikhil Dua	Contact: http://www.ti.com/support	

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